

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	cadouri near eitan.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:04
L2	18	(die near placement) and (wafer or substrate) and (locations) and (process\$3) and (adjust\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:10
L3	3091	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:10
L4	119	(die near placement) and (wafer or substrate) and (locations) and (process\$3) and (adjust\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:12
L5	6	4 and (adjust\$3) near5 (die near placement)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:12
L6	218	(die near3 placement) and (wafer or substrate) and (locations) and (process\$3) and (adjust\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:20
L7	6	6 and (adjust\$3) near5 (die near placement)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:12
L8	6	6 and (adjust\$3) near5 (die near3 placement)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:13
L9	58	6 and (emitt\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:13

L10	3	9 and clamps	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:13
L11	63	6 and (die near3 placement) with (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:15
L12	9	6 and (die near3 placement) with (wafer or substrate) with (locations)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:21
L13	0	6 and (dice near3 placement) with (wafer or substrate) with (locations)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:20
L14	449	(di\$3 near3 placement) and (wafer or substrate) and (locations) and (process\$3) and (adjust\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:21
L15	10	14 and (di\$3 near3 placement) with (wafer or substrate) with (locations)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:22
L16	1112	(di\$3 near3 placement) and (wafer or substrate) and (locations) and (process\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:27
L17	31	16 and (di\$3 near3 placement) with (wafer or substrate) with (locations)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:47
L18	179454	(plac\$5) and (wafer or substrate) and (locations) and (process\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:00
L19	182	18 and (di\$3 near3 plac\$5) with (wafer or substrate) with (locations)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:29

L20	3	18 and (dy\$3 near3 plac\$5) with (wafer or substrate) with (locations)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:28
L21	0	19 and (reticle near3 array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:29
L22	105	19 and (array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:02
L23	579470	22 and clamps	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 16:29
L24	10	22 and clamps	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:02
L25	6283	(di\$3 or dy\$3) near3 (mov\$5) and (wafer or substrate) and (locations) and (process\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:02
L26	2402	(di\$3 or dy\$3) near (mov\$5) and (wafer or substrate) and (locations) and (process\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:02
L27	931	26 and (array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:02
L28	153	27 and clamps	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:06
L29	16	method with (di\$3 or dy\$3) near3 placement.ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:07

L30	2147	(clamp near3 wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:51
L31	149	30 and ((method) with (di\$3) or (dy\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:48
L32	65	31 and opposite	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:49
L33	12340	(clamp with location)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:51
L34	120	(clamp with location) near15 (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:51
L35	64	34 and opposite	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 17:51